**Product data sheet** 

# 1. General description

Silicon Carbide Schottky Diode in 2-lead TO247-2L plastic package, designed for high frequency switched-mode power supplies.



## 2. Features and benefits

- · Highly stable switching performance
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- · Reduced losses in associated MOSFET
- Reduced EMI
- · Reduced cooling requirements
- RoHS compliant

# 3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

## 4. Quick reference data

### Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes		Values		Unit
Absolute	maximum rating						
$V_{RRM}$	repetitive peak reverse voltage				650		V
l <sub>F</sub>	continuous forward current	T <sub>mb</sub> ≤ 163 °C, DC; <u>Fig. 2</u>			10		Α
T <sub>j</sub>	junction temperature			-55 to 175		°C	
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics						
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>		-	1.45	1.70	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>		-	1.80	2.20	V
Dynamic	characteristics						
Q <sub>r</sub>	recovered charge	$I_F = 10 \text{ A; } dI_F/dt = 500 \text{ A/}\mu\text{s; } V_R = 400 \text{ V; } T_j = 25 \text{ °C; } Fig. 7$		-	14.5	-	nC

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		v 14 A
2	Α	anode		K <del>   </del> A 001aaa020
mb	mb	mounting base; connected to cathode	K A TO247-2L	

# 6. Ordering information

### **Table 3. Ordering information**

Type number	Package	Orderable part number	Packing	Small packing	Package	Package
	name		method	quantity	version	issue date
WNSC5D10650W	TO247-2L	WNSC5D10650W6Q	Tube	30	TO247L-2L(L)	10-Nov-2020
					TO247P-2L(P)	31-Mar-2023

# 7. Marking

### Table 4. Marking codes

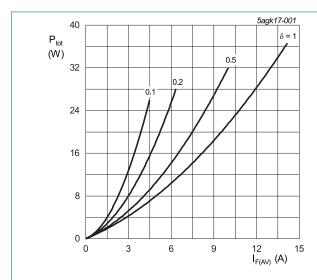
Type number	Marking codes
WNSC5D10650W	WNSC5D 10650W

# 8. Limiting values

**Table 5. Limiting values** 

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			650	V
$V_{RWM}$	crest working reverse voltage			650	V
$V_R$	reverse voltage	DC		650	V
I <sub>F</sub>	continuous forward	T <sub>mb</sub> ≤ 163 °C, DC; <u>Fig. 2</u>		10	Α
	current	T <sub>mb</sub> ≤ 125 °C, DC; <u>Fig. 2</u>		13	Α
		T <sub>mb</sub> ≤ 25 °C, DC; <u>Fig. 2</u>		25	Α
I <sub>FRM</sub>	repetitive peak forward current	$δ = 0.5$ ; $t_p = 25 \mu s$ ; $T_{mb} \le 125 °C$ ; square-wave pulse		20	А
I <sub>FSM</sub>	non-repetitive peak	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		60	Α
	forward current	$t_p$ = 10 µs; $T_{j(init)}$ = 25 °C; square-wave pulse		540	Α
l <sup>2</sup> t	I <sup>2</sup> t for fusing	sine-wave pulse; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 10 \text{ ms}$		18	A <sup>2</sup> s
T <sub>stg</sub>	storage temperature			-55 to 175	°C
T <sub>j</sub>	junction temperature			-55 to 175	°C



 $I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$  $V_o = 1.103 \text{ V}; R_s = 0.1048 \Omega$ 

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

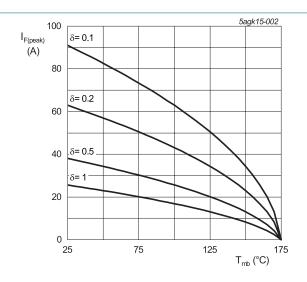
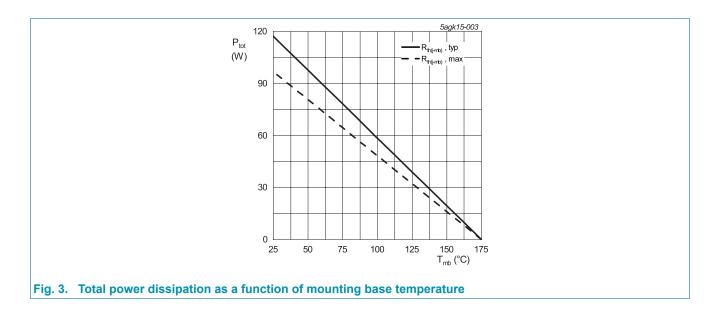


Fig. 2. Current derating as a function of mounting base temperature



## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 4		-	1.28	1.55	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air		-	50	-	K/W

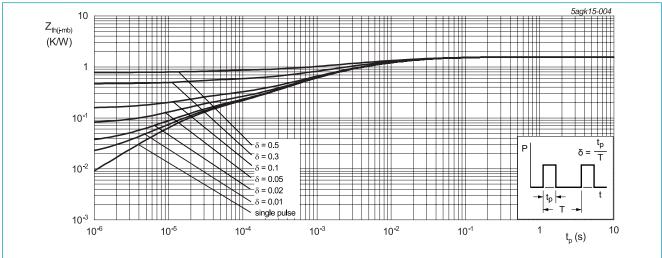
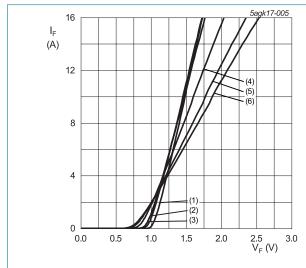


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	aracteristics				·		
V <sub>F</sub>	forward current	I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>		-	1.45	1.70	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>		-	1.80	2.20	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 175 °C; <u>Fig. 5</u>		-	2.00	2.30	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>		-	0.5	50	μA
		V <sub>R</sub> = 650 V; T <sub>j</sub> = 175 °C; <u>Fig. 6</u>		-	25	250	μA
Dynamic	characteristics						
Q <sub>r</sub>	recovered charge	$I_F = 10 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	14.5	-	nC
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C		-	323	-	pF
		f = 1 MHz; V <sub>R</sub> = 300 V; T <sub>j</sub> = 25 °C		-	38	-	pF
		f = 1 MHz; V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C		-	35	-	pF
E <sub>as</sub>	non-repetitive avalanche energy	I <sub>R</sub> = 4.9 A; L = 5 mH; T <sub>j(init)</sub> = 25 °C		60	-	-	mJ



 $V_o$  = 1.103 V;  $R_s$  = 0.1048  $\Omega$ 

(1)  $T_j = -55$  °C; typical values (2)  $T_j = 0$  °C; typical values

(3) T<sub>i</sub> = 25 °C; typical values

(4) T<sub>i</sub> = 100 °C; typical values

(5)  $T_j = 150$  °C; typical values (6)  $T_j = 175$  °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

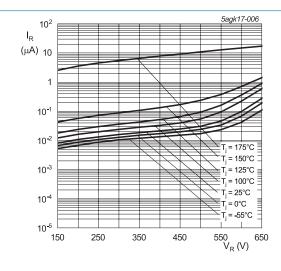


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

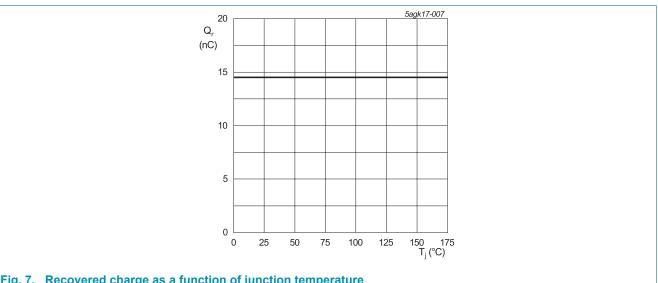
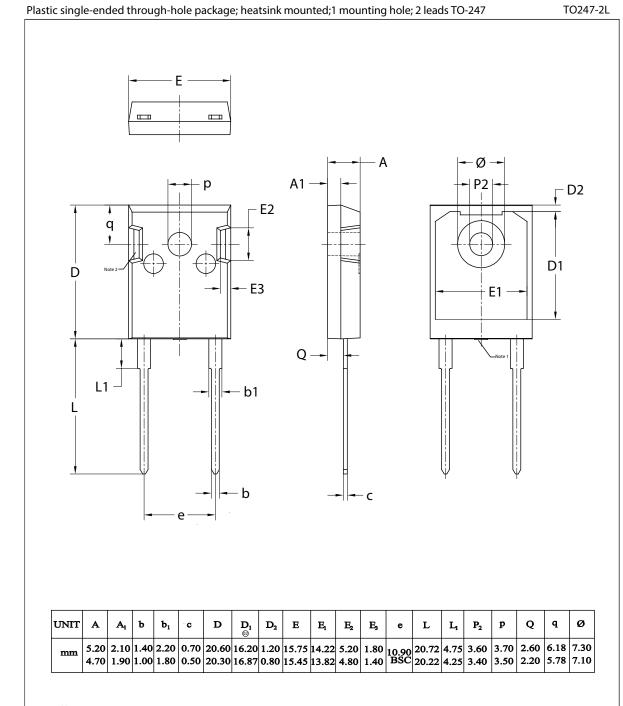


Fig. 7. Recovered charge as a function of junction temperature

# 11. Package outline



### Note:

- 1. Mold resin protrusion max 0.127mm.
- Metal exposed with Sn plating.

## 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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